

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chi-Yuan HSU	08/26/2008
RECEIVING PARTY DATA	
Name:	Chi-Yuan HSU
Street Address:	2F, No. 23, Wucyuan Rd., Wugu Township
City:	Taipei County
State/Country:	TAIWAN
Name:	iLED Photoelectronics, Inc.
Street Address:	2F, No.23, Wucyuan Rd., Wugu Township
City:	Taipei County
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12206523
CORRESPONDENCE DATA	
Fax Number:	(361)579-9966
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	281-2659279
Email:	BS@PAT-BANGSHIA.COM
Correspondent Name:	Dr. BANGER SHIA
Address Line 1:	102 Lindencrest Ct.
Address Line 4:	Sugar Land, TEXAS 77479-5201
ATTORNEY DOCKET NUMBER:	CFP-3974 (C-467)
NAME OF SUBMITTER:	BANGER SHIA

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PATENT
REEL: 021497 FRAME: 0113

Total Attachments: 3

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ASSIGNMENT DEED

ASSIGNOR:

Hsu, Chi-Yuan

2F., No.23, Wucyuan Rd., Wugu Township, Taipei County 248,

Taiwan (R.O.C.)

ASSIGNEE:

Hsu, Chi-Yuan

2F., No.23, Wucyuan Rd., Wugu Township, Taipei County 248,

Taiwan (R.O.C.)

iLED photoelectronics, Inc.

2F., No.23, Wucyuan Rd., Wugu Township, Taipei County 248,

Taiwan (R.O.C.)

Whereas, _____ Hsu, Chi-Yuan
whose address is set forth above (hereinafter referred to as "Assignor", consideration of
payment to it of the sum of Ten U.S. Dollars (U.S.\$10.00) and for other good and valuable
consideration, receipt and sufficiency of which are acknowledged hereby; received from

Hsu, Chi-Yuan / iLED photoelectronics, Inc. _____, whose
address is set forth above (hereinafter referred to as "Assignee");

Assignor has sold, assigned, and conveyed and hereby does evidence such sale,
assignment and conveyance unto said Assignee, its successors and/or assigns, Assignor's

entire right, title and interest —

(1) In and to an invention entitled _____
PACKAGE METHOD AND STRUCTURE FOR A LIGHT EMITTING DIODE
MULTI-LAYER MODULE

as described in United States Patent Application Serial No. _____, filed on _____; which issued into United States Letters Patent No. _____ on _____, including the right to recover for past infringements thereof.

(2) In and to said Application for Letters Patent and said Letters Patent No. _____ which issued _____ on said Application and any and all other applications for letters patent of the United States of America (including renewal, divisional, continuation, continuation-in-part, substitute and reissue applications) based upon said invention, including extensions and reissues, if any, to the full ends of the terms for which said Letters Patent of the United states has been granted.

(3) In and to all applications for said invention, now or hereafter filed in countries foreign to the United States of America, and in and to any and all letters patent granted on said applications to the full ends of the terms for which said Letters Patent may be granted.

Assignor further covenants and agrees that it has not executed and will not execute any documents in conflict herewith, and it further agrees that it will at any time upon request by Assignees execute and deliver any and all papers that may be necessary or desirable to perfect title to said invention, Application for Letters Patent, and the Letters Patent to Assignees, and if Assignees desires to file one or more divisional, continuation, continuation-in-part, or substitute applications of or for said Letters Patent of the United States of America, or to secure a reissue or extension of such Letters Patent, or to file a disclaimer relating thereto, Assignors will upon request by Assignees sign all papers, make all rightful oaths and do all lawful acts requisite of it for such reissue or extension, or the procuring thereof, and for the filing of such disclaimer, but at the expense of Assignees, its successors and/or assigns.

Assignor further agrees that it will at any time upon request by Assignee communicate

And the Commissioner of Patents and Trademarks of the United States of America and comparable officials in countries foreign to the United States of America to record and/or issue said Letters Patent, and the like to Assignee as assignee of Assignor's entire right, title and interest therein.

Signed at TAIPEI, TAIWAN this 26 day of AUG. 2008.

Assignor:

By : HSU CHI-YUAN _____

Name : HSU, CHI-YUAN

Title : INVENTOR

Date : 08/26/2008

Witness:

Signature: _____

Name :

Address :

Date: